

OCT 11 2006

Patent

Customer No.: 31561
Docket No. 11579-US-PA
Application No.: 10/710,419

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Min-Lung Huang
 Application No. : 10/710,419
 Filed : July 9, 2004
 For : WAFER STRUCTURE AND BUMPING PROCESS
 THEREOF
 Art Unit : 2814
 Examiner : MAI, ANH D.

TRANSMITTAL LETTER

+1-571-273-8300 (Via Fax: 2+8 pages)

Assistant Commissioner for Patents
 Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated July 14, 2006 (Paper No.:20060710),
 transmitted herewith please find the Response in (8) pages.

The Applicant is NOT entitled to a status as a Small Entity; accordingly, please
 charge the following fees to the Deposit Account No.: 50-2620 (Order No.:
 11579-US-PA),

Fees are calculated as follows:

<input type="checkbox"/> Extra Claims Fee :						
	NUMBER FILED	CLAIMS FILED HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	FEE	
Total Claims	13	MINUS 22	= 0	× \$ 50	= \$ 0/	
Independent Claims	1	MINUS 2	= 0	× \$ 200	= \$ 0/	
<input type="checkbox"/> [1/2/3] month(s) extension of time is hereby requested.					= \$ 0/ 120/ 450/ 1020	
<input type="checkbox"/> Terminal Disclaimer Fee					= \$ 0/ 130	
<input type="checkbox"/> Fee regarding Submission of an Information Disclosure Statement .					= \$ 0/ 180	
Total:					= \$ 0	

If the payment is not fully covered in response thereof, the Commissioner is
 authorized to charge any fees required in connection with the filing of this paper to
 account No.: 50-2620 (Order No.: 11579-US-PA).

Patent

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Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: Oct. 11, 2006

By: Belinda Lee
Belinda Lee
Registration No.: 46,863

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: MAI, Anh D.

Group Art Unit: 2814

In re PATENT APPLICATION of
Applicants : HUANG, Min-Lung

Serial No. : 10/710,419

Filed : July 9, 2004

**For : Wafer Structure And Bumping
Process Thereof**

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AMENDMENT

Attorney Docket: 11579-US-PA

The Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 11579-US-PA)

AMENDMENTS AND RESPONSE TO OFFICE ACTION

United States Patent and Trademark Office
Customer Service Window
Mail Stop **Amendment**
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Dear Sir:

The Office Action dated July 14, 2006, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.